

- Provides High-Voltage Differential SCSI From Single-Ended Controller When Used With the SN75970B Control Transceiver
- Meets or Exceeds the Requirements of EIA Standard RS-485 and ISO-8482 Standards
- ESD Protection on Bus Pins to 12 kV
- Packaged in Shrink Small-Outline Package with 25 mil Terminal Pitch and Thin Small-Package with 20 mil Terminal Pitch
- Low Disabled-Supply Current 32 mA Typ
- Thermal Shutdown Protection
- Positive- and Negative-Current Limiting
- Power-Up/-Down Glitch Protection
- Open-Circuit Failsafe Receivers

description

The SN75971B SCSI differential converter-data is a 9-channel RS-485 transceiver. When used in conjunction with its companion control transceiver, the SN75970B, the resulting chip set provides the superior electrical performance of differential SCSI from a single-ended SCSI bus or controller. A 16-bit Ultra-SCSI (or Fast-20) SCSI bus can be implemented with just three devices (two data and one control) in the space efficient, 56-pin, shrink small-outline package (SSOP) or thin shrink small outline package (TSSOP) and a few external components. An 8-bit SCSI bus requires only one data and one control transceiver.

The SN75971B is available in a B2 (20 Mxfer) version and a B1 (10 Mxfer) version.

In a typical differential SCSI node, the SCSI controller provides an enable for each external RS-485 transceiver channel. This could require as many as 27 extra terminals for a 16-bit differential bus controller or relegate a 16-bit, single-ended controller to only an 8-bit differential bus. Using the standard nine SCSI control signals, the SN75970B control transceiver decodes the state of the bus and enables the SN75971B data transceiver to transmit the single-ended SCSI input signals (A side) differentially to the cable or receive the differential cable signals (B side) and drive the single-ended outputs to the controller.

A reset function, which disables all outputs and clears internal latches, can be accomplished from two external inputs and two internally-generated signals. $\overline{\text{RESET}}$ (reset) and DSENS (differential sense) are available to external circuits for a bus reset or to disable all outputs should a single-ended cable be inadvertently connected to a differential connector. Internally-generated power-up and thermal-shutdown signals have the same affect when the supply voltage is below approximately 3.5 V or the junction temperature exceeds 175°C.

DGG OR DL PACKAGE
(TOP VIEW)

SDB	1	56	DSENS
DRVBUS	2	55	RESET
GND	3	54	GND
ADBP-	4	53	BDBP-
NC	5	52	BDBP+
ADB7-	6	51	BDB7-
NC	7	50	BDB7+
ADB6-	8	49	BDB6-
NC	9	48	BDB6+
ADB5-	10	47	BDB5-
NC	11	46	BDB5+
V _{CC}	12	45	V _{CC}
GND	13	44	GND
GND	14	43	GND
GND	15	42	GND
GND	16	41	GND
GND	17	40	GND
V _{CC}	18	39	V _{CC}
ABD4-	19	38	BDB4-
NC	20	37	BDB4+
ADB3-	21	36	BDB3-
NC	22	35	BDB3+
ADB2-	23	34	BDB2-
NC	24	33	BDB2+
ADB1-	25	32	BDB1-
NC	26	31	BDB1+
ADB0-	27	30	BDB0-
NC	28	29	BDB0+

Pins 13 – 17 and 40 – 44 are connected together to the package lead frame and to signal ground.

NC – No internal connection



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

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SN75971B

SCSI DIFFERENTIAL CONVERTER-DATA

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description (continued)

The SCSI, differential, converter-data chip operates in two modes depending on the state of the DRVBUS input. With DRVBUS low, a bidirectional latch circuit sets the direction of data transfer. Each data bit has its own latch, and each bit's direction is independent of all other bits. When neither the single-ended nor the differential sides are asserted, the latch disables both A- and B-side output drivers. When the input to either side is asserted, the latch enables the opposite side's driver and sets data flow from the asserted input to the opposite side of the device. When the input deasserts, the latch maintains the direction until the receiver on the enabled driver detects a deassertion. The latch then returns to the initial state. No parity checking is done by this device; the parity signal passes through the device like other data signals do.

When DRVBUS is high, direction is determined by the SDB signal. However, a change in SDB does not always immediately change the direction. When DRVBUS first asserts, the direction indicated by SDB is latched and takes effect immediately. When SDB changes while DRVBUS is high, the drivers that were on immediately turn off. However, the other driver set does not turn on until the receivers sense a deasserted state on all nine data lines. This is done to prevent the active drivers from turning on until all other drivers are off and the terminators pull the lines to a deasserted state.

The single-ended SCSI bus interface consists of CMOS, bidirectional inputs and outputs. The drivers are rated to ± 16 mA of output current. The receiver inputs are pulled high with approximately 4 mA to eliminate the need for external pullup resistors for the open-drain outputs of most single-ended SCSI controllers. The single-ended side of the device is not intended to drive the SCSI bus directly.

The differential SCSI bus interface consists of bipolar, bidirectional inputs and outputs that meet or exceed the requirements of EIA-485 and ISO 8482-1982/TIA TR30.2 referenced by American National Standard of Information Systems (ANSI) X3.131-1994 Small Computer System Interface-2 (SCSI-2) and SCSI-3 Fast-20 Parallel Interface (Fast-20) X3.277:1996.

The SN75971B is characterized for operation over the temperature range of 0°C to 70°C.

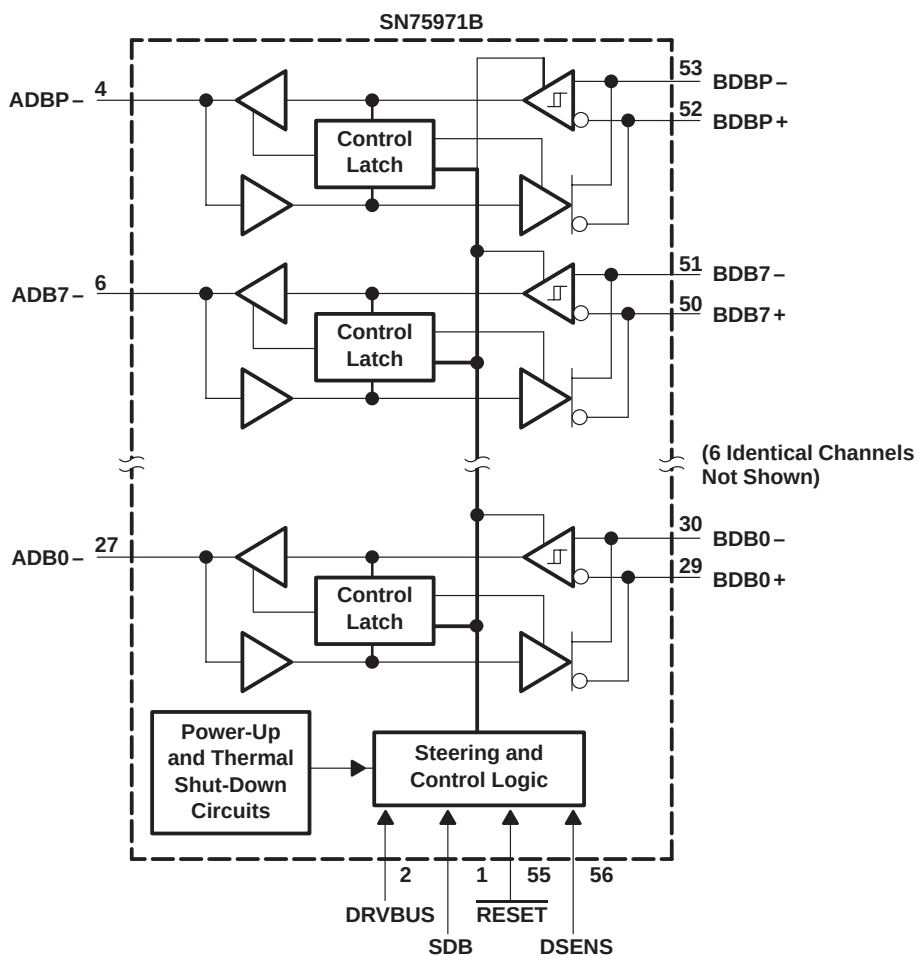
Terminal Functions

TERMINAL		I/O	DESCRIPTION
NAME	NO.		
ADBn-, where n = {0,1,2,3,4,5,6,7,P}	4, 6, 8, 10, 19, 21, 23, 25, 27	I/O, Single-ended SCSI voltage levels, Strong pullup	Bidirectional I/O for data and parity bits to and from the single-ended SCSI controller. As outputs, these terminals can source or sink 16 mA. As inputs, they are pulled up with about 4-mA to eliminate external resistors.
BDBn+, where n = {0,1,2,3,4,5,6,7,P}	29, 31, 33, 35, 37, 46, 48, 50, 52	I/O, RS-485, Weak pulldown	Bidirectional I/O for data and parity to and from the differential SCSI bus.
BDBn-, where n = {0,1,2,3,4,5,6,7,P}	30, 32, 34, 36, 38,47, 49, 51, 53	I/O, RS-485, Weak pulldown	Bidirectional I/O for the complement of data and parity to and from the differential SCSI bus.
DRVBUS	2	Input, TTL levels, Weak pulldown	A high-level logic signal from the control transceiver enables either the single-ended or differential drivers as directed by SDB.
DSSENS	56	Input, TTL levels, Weak pullup	A low-level input initializes the internal latches and disables all drivers.
RESET	55	Input, TTL levels, Weak pullup	A low-level input initializes the internal latches and disables all drivers.
SDB	1	Input, TTL levels, Weak pulldown	A high-level logic signal from the control transceiver sends data from the differential bus to the single-ended bus. A low-level signal reverses the flow.



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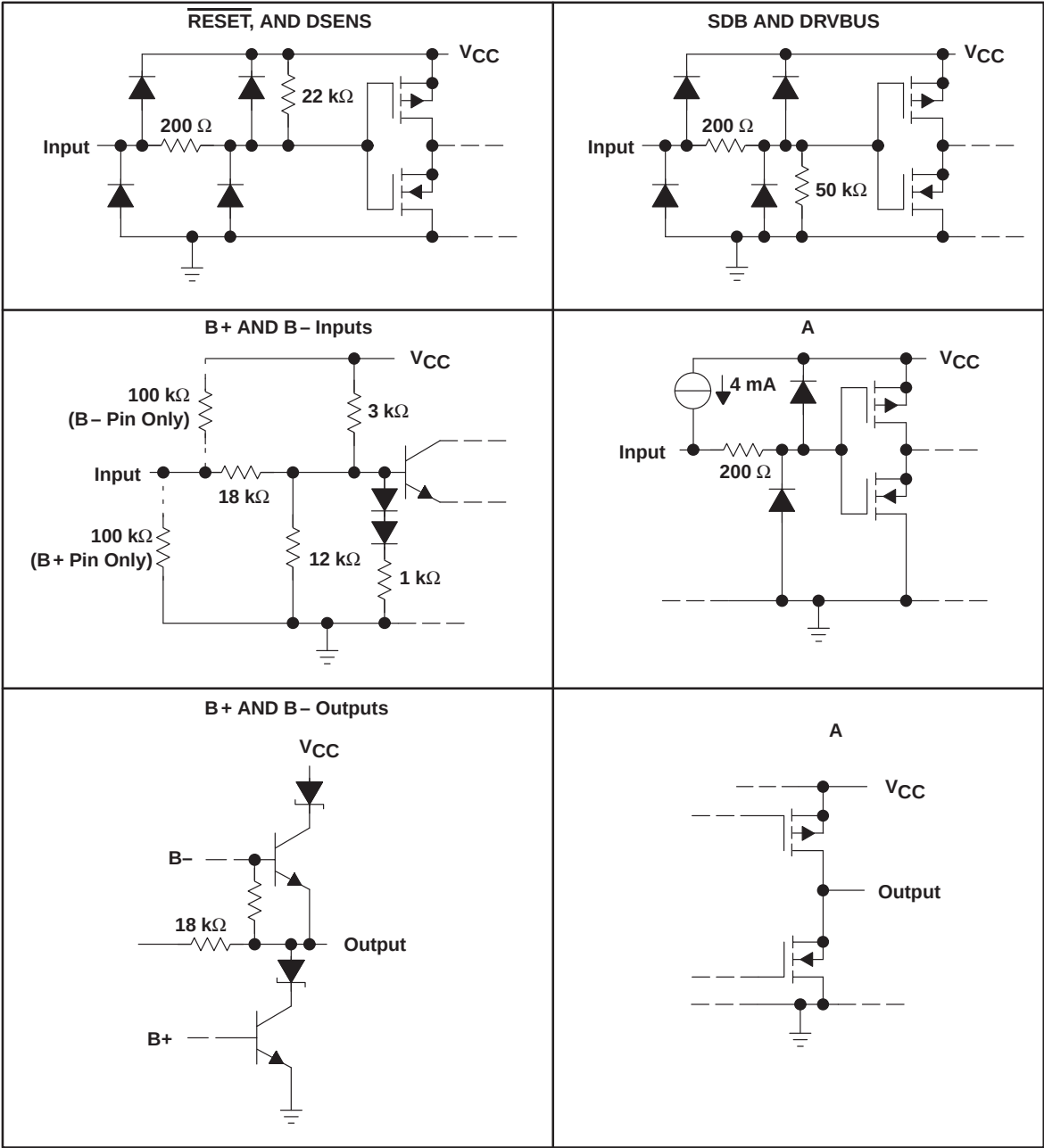
functional block diagram



SN75971B
SCSI DIFFERENTIAL CONVERTER-DATA

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schematics of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC} (see Note 1)	–0.3 V to 7 V
Differential bus voltage range (B side)	–10 V to 15 V
Single-ended bus voltage range (A side and control inputs)	–0.3 V to 7 V
Continuous total power dissipation (see Note 2)	Internally Limited (see Dissipation Rating Table)
Electrostatic discharge (see Note 3): Class 2 A (all pins)	4 kV
Class 2 B (all pins)	400 V
Class 3 A (B-side and GND)	12 kV
Class 3 B (B-side and GND)	400 V
Operating free-air temperature range, T_A	0°C to 70°C
Storage temperature range, T_{stg}	65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values are with respect to GND.
2. The maximum operating junction temperature is internally limited. Use the dissipation rating table to operate below this temperature.
3. This absolute maximum rating is tested in accordance with MIL-STD-883C, Method 3015.7.

DISSIPATION RATING TABLE

PACKAGE	$T_A \leq 25^\circ\text{C}$ POWER RATING	DERATING FACTOR [‡] ABOVE $T_A = 25^\circ\text{C}$	$T_A = 70^\circ\text{C}$ POWER RATING
DGG	3333 mW	26.7 mW/°C	2133 mW
DL	3709 mW	29.7 mW/°C	2374 mW

[‡] This is the inverse of the traditional junction-to-case thermal resistance ($R_{\theta JA}$) for High-K (per JEDEC) PCB installations.

recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V_{CC}		4.75	5	5.25	V
High-level input voltage, V_{IH}	A side and control	2			V
Low-level input voltage, V_{IL}	A side and control			0.8	V
Voltage at any bus terminal (separately or common-mode), V_O or V_I	B side			12 –7	V
High-level output current, I_{OH}	A side			–16	mA
Low-level output current, I_{OL}	A side			16	mA
Operating case temperature, T_C		0		125	°C
Operating free-air temperature, T_A		0		70	°C

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electrical characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER			TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT
V _{OD(H)}	Driver high-level differential output voltage		See Figure 1		–1	–2.2		V
V _{OD(L)}	Driver low-level differential output voltage		See Figure 1		1	1.8		V
V _{OH}	High-level output voltage	A side	V _{ID} = –200 mV, I _{OH} = –16 mA		2.5	4.2		V
		B side	I _{OH} = –60 mA		3.4			
V _{OL}	Low-level output voltage	A side	V _{ID} = 200 mV, I _{OL} = 16 mA		0.4		0.8	V
		B side	I _{OL} = 60 mA		1.6			
V _{IT+}	Receiver positive-going differential input threshold voltage	B side	I _{OH} = –16 mA See Figure 2		0.2			V
V _{IT–}	Receiver negative-going differential input threshold voltage		I _{OL} = 16 mA See Figure 2		–0.2 [§]			V
V _{hys}	Receiver input hysteresis voltage (V _{IT+} – V _{IT–})				35	45		mV
I _I	Bus input current	B or $\overline{B}$	V _I = 12 V, Other input at 0 V	V _{CC} = 5 V	0.6		1	mA
				V _{CC} = 0	0.7		1	
			V _I = –7 V, Other input at 0 V	V _{CC} = 5 V	–0.5		–0.8	mA
				V _{CC} = 0	–0.4		–0.8	
I _{IH}	High-level input current	A side	V _{IH} = 2 V		–2	–5	–8	mA
		$\overline{\text{RESET}}$, DSENS			–70		–100	
		SDB, DRVBUS			25			
I _{IL}	Low-level input current	A side	V _{IL} = 0.8 V		–6	–9	mA	
		$\overline{\text{RESET}}$, DSENS			–66			–100
		SDB, DRVBUS			±30			
I _{OS}	Short-circuit output current	B side	V _O = 5 V and 0		±250			mA
I _{OZ}	High-impedance-state output current	A side			–2	–5	–8	
		B side					–6	
I _{CC}	Supply current	Disabled	$\overline{\text{RESET}}$ at 0.8 V, Others open		38	46	mA	
		B to A Enabled	SDB and DRVBUS at 2 V, V _{ID} = –1 V, No load		39	50		
		A to B Enabled	SDB at 0.8 V, DRVBUS at 2 V, No load		32	66		
C _O	Output capacitance		V _I = 0.6 sin(2π × 10 ⁶ t) + 1.5 V, BDBn to GND		18	21		pF
C _{pd}	Power dissipation capacitance [‡]		B to A, One channel		40			pF
			A to B, One channel		100			pF

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C.

[‡] C_{pd} determines the no-load dynamic current consumption, I_S = C_{pd} × V_{CC} × f + I_{CC}.

[§] The algebraic convention with the least positive (more negative) limit is designated minimum, is used in this data sheet for the differential input voltage only.



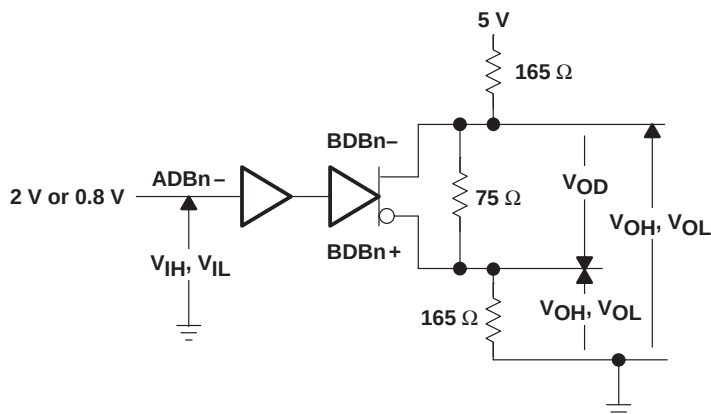
switching characteristics over recommended of operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	MAX	UNIT
t_{d1}, t_{d2} Delay time, A to B, high- to low-level or low- to high-level output	SN75971B1	See Figures 3 and 4	3	14	ns
		$V_{CC} = 5\text{ V}, T_A = 25^\circ\text{C},$ See Figures 3 and 4	4	12	
		$V_{CC} = 5\text{ V}, T_A = 70^\circ\text{C},$ See Figures 3 and 4	4.9	12.9	
	SN75971B2	See Figures 3 and 4	5	12	
		$V_{CC} = 5\text{ V}, T_A = 25^\circ\text{C},$ See Figures 3 and 4	6.2	10.2	
		$V_{CC} = 5\text{ V}, T_A = 70^\circ\text{C},$ See Figures 3 and 4	6.9	10.9	
t_{d3}, t_{d4} Delay time, B to A, high- to low-level or low- to high-level output	SN75971B1	See Figures 5 and 6	5.4	18.1	ns
		$V_{CC} = 5\text{ V}, T_A = 25^\circ\text{C},$ See Figures 5 and 6	6.5	15.4	
		$V_{CC} = 5\text{ V}, T_A = 70^\circ\text{C},$ See Figures 5 and 6	7.2	16.1	
	SN75971B2	See Figures 5 and 6	7.7	15	
		$V_{CC} = 5\text{ V}, T_A = 25^\circ\text{C},$ See Figures 5 and 6	8.7	13.2	
		$V_{CC} = 5\text{ V}, T_A = 70^\circ\text{C},$ See Figures 5 and 6	9.4	13.9	
$t_{sk(pp)}$ Skew, part-to-part [†]	SN75971B1	A to B See Figures 5 and 6		8	ns
		B to A See Figures 5 and 6		9	
	SN75971B2	A to B See Figures 5 and 6		4	
		B to A See Figures 5 and 6		5	
$t_{sk(p)}$ Pulse skew [‡]				4	ns
t_{dis1} Disable time, A to B		See Figures 3 and 4		200	ns
t_{dis2} Disable time, B to A		See Figures 5 and 6		35	ns
t_{en1} Enable time, A to B		See Figures 3 and 4		65	ns
t_{en2} Enable time, B to A		See Figures 5 and 6		65	ns
$t_{en(TX)}$ Enable time, receive-to-transmit		See Figure 7		142	ns

[†] Part-to-part skew is the magnitude of the difference in propagation delay times between any two devices when both operate with the same supply voltages, the same temperature, and the same loads.

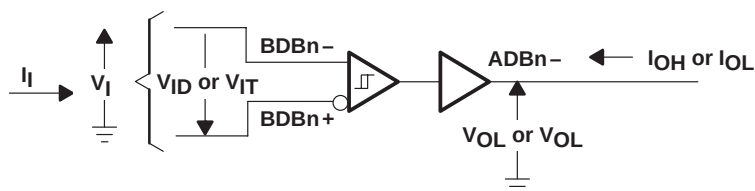
[‡] Pulse skew is the difference between the high-to-low and low-to-high propagation delay times of any single channel.

PARAMETER MEASUREMENT INFORMATION



- NOTES: A. Resistance values are in ohms with a tolerance of $\pm 5\%$.
B. All input voltage levels are held to within 0.01 V.
C. The logical function is set with SDB at 0.8 V, DRVBUS at 3.5 V, and all others left open.

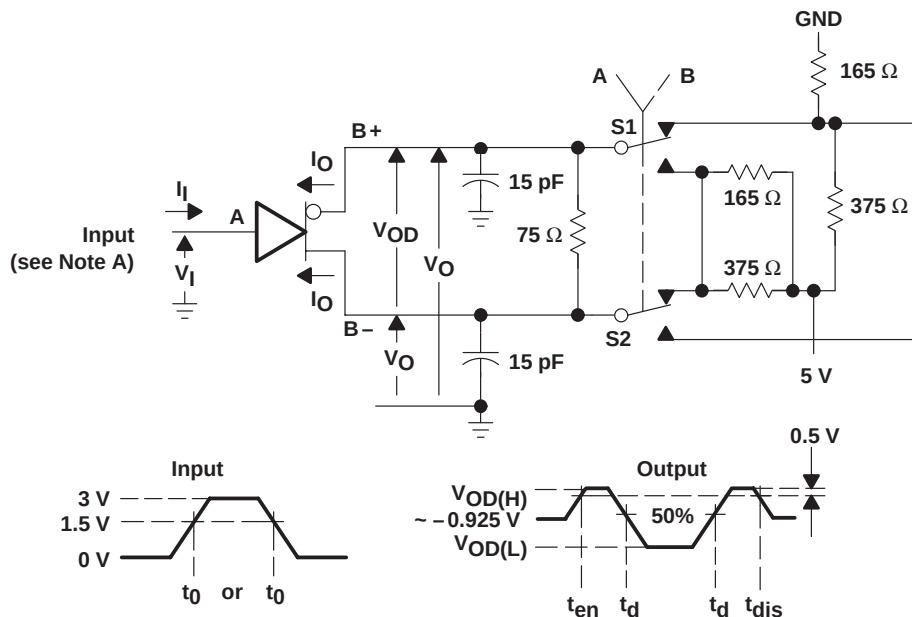
Figure 1. Differential Driver V_{OD} , V_{OH} , and V_{OL} Test Circuit



- NOTES: A. Resistance values are in ohms with a tolerance of $\pm 5\%$.
B. All input voltage levels are held to within 0.01 V.
C. The logical function is set with SDB and DRVBUS at 3.5 V, and all others left open.

Figure 2. Single-Ended Driver V_{OH} , V_{OL} , V_{IT+} , and V_{IT-} Test Circuit

PARAMETER MEASUREMENT INFORMATION



- NOTES: A. The input pulse is supplied by a generator having the following characteristics: $PRR \leq 1$ MHz, $45\% < \text{duty cycle} < 50\%$, $t_f \leq 1$ ns, $t_r \leq 1$ ns, $Z_O = 50 \Omega$.
 B. C_L includes probe and jig capacitance.
 C. Resistance values are in ohms with a tolerance of $\pm 5\%$.
 D. All input voltage levels are held to within 0.01 V.

Figure 3. A to B Propagation Delay Time Test Circuit

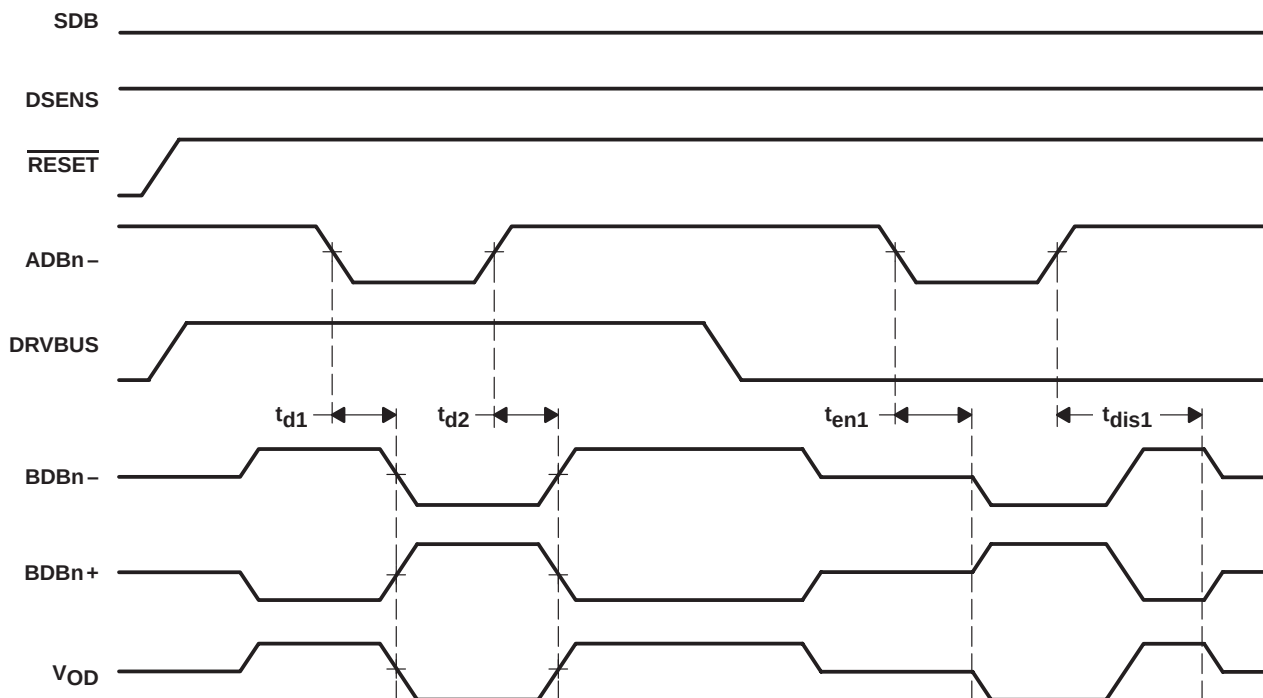
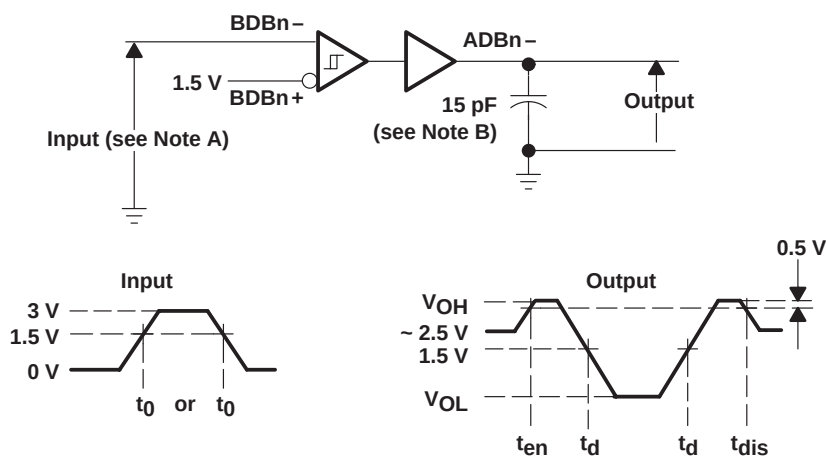


Figure 4. A to B Timing Waveforms

PARAMETER MEASUREMENT INFORMATION



- NOTES: A. The input pulse is supplied by a generator having the following characteristics: $PRR \leq 1 \text{ MHz}$, $45\% < \text{duty cycle} < 50\%$, $t_r \leq 1 \text{ ns}$, $t_f \leq 1 \text{ ns}$, $Z_O = 50 \Omega$.
 B. C_L includes probe and jig capacitance.
 C. Resistance values are in ohms with a tolerance of $\pm 5\%$.
 D. All input voltage levels are held to within 0.01 V.

Figure 5. B to A Propagation Delay Time Test Circuit

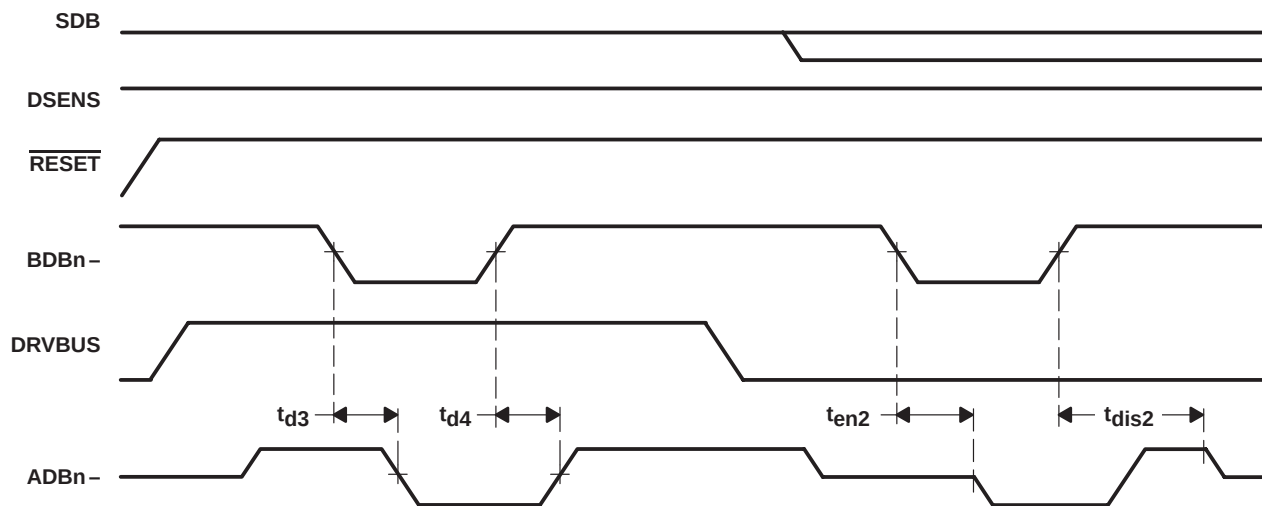


Figure 6. B to A Timing Waveforms

PARAMETER MEASUREMENT INFORMATION

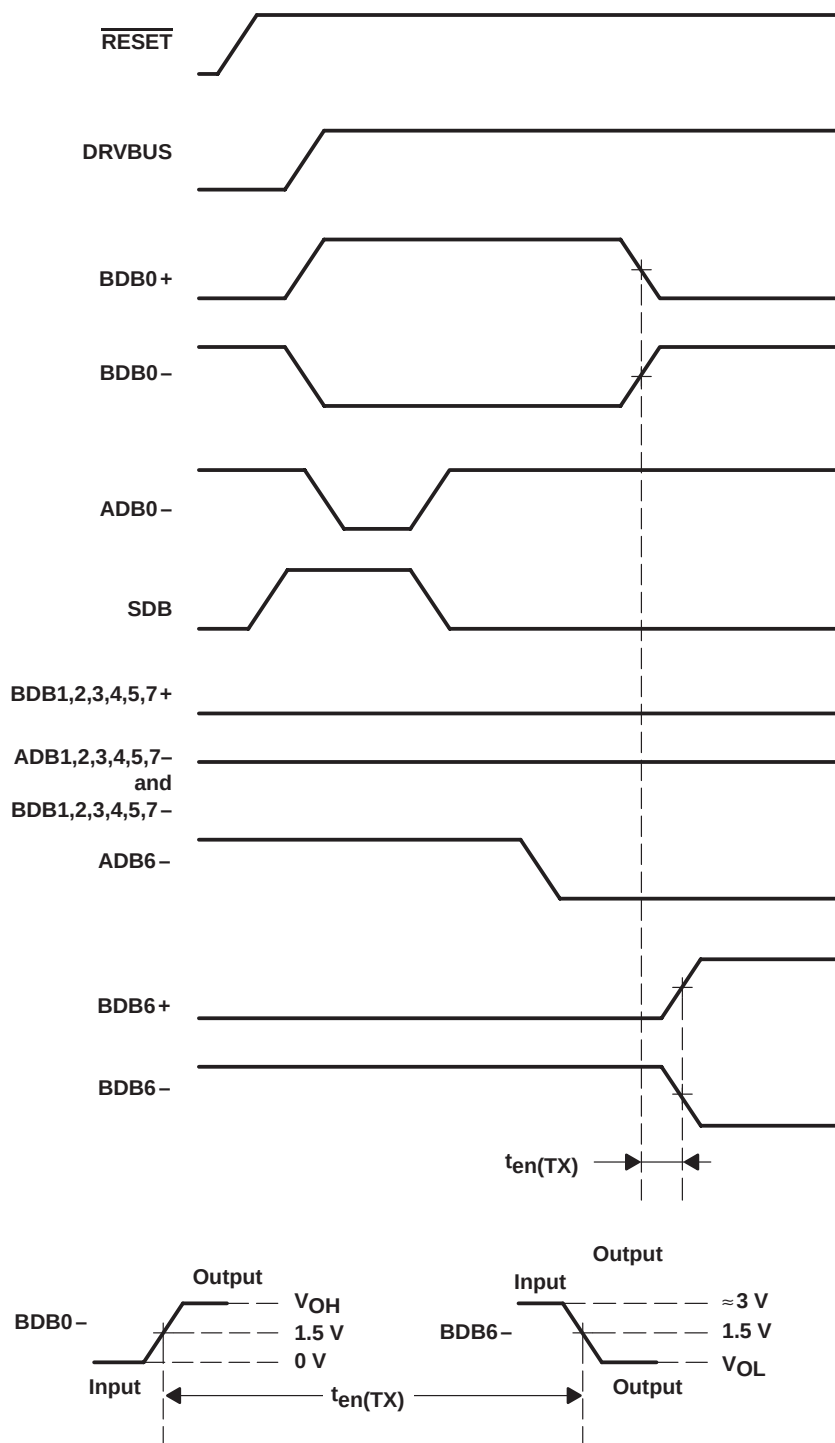


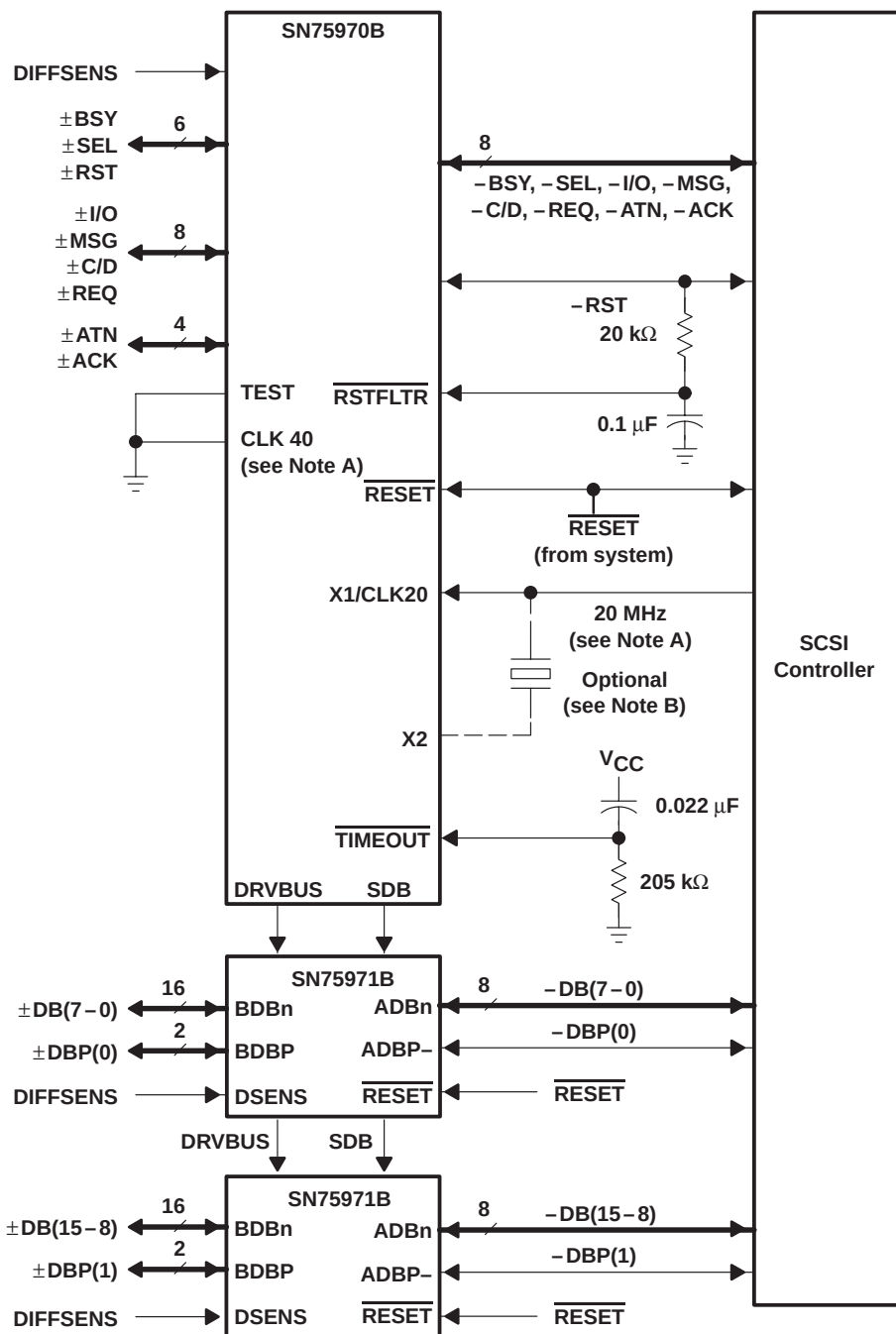
Figure 7. Receive-to-Transmit ($t_{en(TX)}$) Timing Waveforms

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APPLICATION INFORMATION



NOTES: A. When using the 40-MHz clock input, X1 must be connected to V_{CC} .

B. The oscillator cell of the SN75970B is for a series-resonant crystal and requires approximately 10 pF (including fixture capacitance) from X1 and X2 to ground in order to function.

Figure 8. Typical Application of the SN75970B and SN75971B

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN75971B2DL	Active	Production	SSOP (DL) 56	20 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	0 to 70	SN75971B2
SN75971B2DL.A	Active	Production	SSOP (DL) 56	20 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	0 to 70	SN75971B2

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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